

PCN# 20181108001.1 Qualification of MIHO8 as an additional Wafer Fab Site option for select devices Change Notification / Sample Request

Date:November 15, 2018To:PREMIER FARNELLPCN

Dear Customer:

This is an announcement of a change to a device that is currently offered by Texas Instruments. The details of this change are on the following pages.

We request you acknowledge receipt of this notification within **30** days of the date of this notice. Lack of acknowledgement of this notice within 30 days constitutes acceptance of the change. If you require samples or additional data to support your evaluation, please request within 30 days.

The changes discussed within this PCN will not take effect any earlier than **90** days from the date of this notification, unless customer agreement has been reached on an earlier implementation of the change. This notification period is per TI's standard process.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the life time buy offering/discontinuance plan.

For questions regarding this notice, contact your local Field Sales Representative or the PCN Manager (<u>PCN ww admin team@list.ti.com</u>).

PCN Team SC Business Services

20181108001.1 Attachment: 1

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, these are the devices that you have purchased within the past twenty-four (24) months. The corresponding customer part number is also listed, if available.

DEVICE UCC21225ANPLT

CUSTOMER PART NUMBER

OCC21225ANI LI

Technical details of this Product Change follow on the next page(s).

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						Nov 15, 2018		
Title: Qualification of MIHO8 as an additional Wafer Fab Site option for select devices in LBC8LV Technology								
act:	PCN Manager		1	Dept:		Quality S	Services	
nip Date:	Feb 15, 2019			Estimated Sample			Date provided at sample	
te						Assembly	Materials	
	Electrica	l Spe	ecification			Mechanical Specification		
	Packing/Shipping/Labeling							
					_	Wafer Bump Process		
ite						Wafer Fab Process		
Change		PCN	Details					
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Current Site	tes Additional S				Sites			
Process			Additional Process Fab Site			/afer meter		
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provided in the	e Qual Data S	Secti	on.	-				
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Product Affected:						
UCC21225ANPL	UCC21225ANPLR	UCC21225ANPLT				

Qualification Report

UCC21225ANPLR MIHO Offload Approve Date 22-Oct-2018

Product Attributes

Attributes	Qual Device: <u>UCC21225ANPLR</u>	QBS Product Reference: <u>UCC21225ANPL</u>	QBS Process Reference: <u>UCC21520ADWR</u>	QBS Process Reference: UCC21520AQDWRQ
Assembly Site	TIPI	TIPI	DAL	TITL
Package Family	LGA	LGA	-	SOIC; 7.5 x 10.3 MM
Flammability Rating	UL 94 V-0	UL 94 V-0	-	-
Wafer Fab Supplier	MIHO 8, MIHO8	DMO5	MH8	MIHO
Wafer Fab Process	LBC8LV-ISO	LBC8LVISO	LBC8LVISO	LBC8LVISO

- QBS: Qual By Similarity

- Qual Device UCC21225ANPLR is qualified at LEVEL3-260CG

- Device UCC21225ANPLR contains multiple dies.

Qualification Results Data Displayed as: Number of lots / Total sample size / Total failed

Туре	Test Name / Condition	Duration	Qual Device: UCC21225ANPLR	QBS Product Reference: UCC21225ANPL	QBS Process Reference: <u>UCC21520ADWR</u>	QBS Process Reference: <u>UCC21520AQDWRQ</u>
AC	Autoclave 121C	96 Hours	-	-	-	1/77/0
CDM	ESD - CDM	2000 V	1/3/0	-	1/3/0	-
ED	Electrical Characterization	Per Datasheet Parameters	Pass	Pass	-	Pass
HAST	Biased HAST, 110C/85%RH	264 Hours	-	3/231/0	-	-
HAST	Biased HAST, 130C/85%RH	96 Hours	-	-	-	1/77/0
HBM	ESD - HBM	5000 V	1/3/0	-	1/3/0	-
HTOL	Life Test, 125C	1000 Hours	-	-	-	1/77/0
HTSL	High Temp Storage Bake 150C	500 Hours	-	3/231/0	-	-
LU	Latch-up	Per JESD78	-	-	1/6/0	-
тс	Temperature Cycle, -65/150C	500 Cycles	1/77/0	2/184/0	-	1/77/0

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable

- The following are equivalent HTOL options based on an activation energy of 0.7eV: 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours

- The following are equivalent HTSL options based on an activation energy of 0.7eV: 150C/1k Hours, and 170C/420 Hours

- The following are equivalent Temp Cycle options per JESD47: -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: http://www.ti.com/

Green/Pb-free Status:

Qualified Pb-Free (SMT) and Green

For questions regarding this notice, e-mails can be sent to the regional contacts shown below, or you can contact your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com